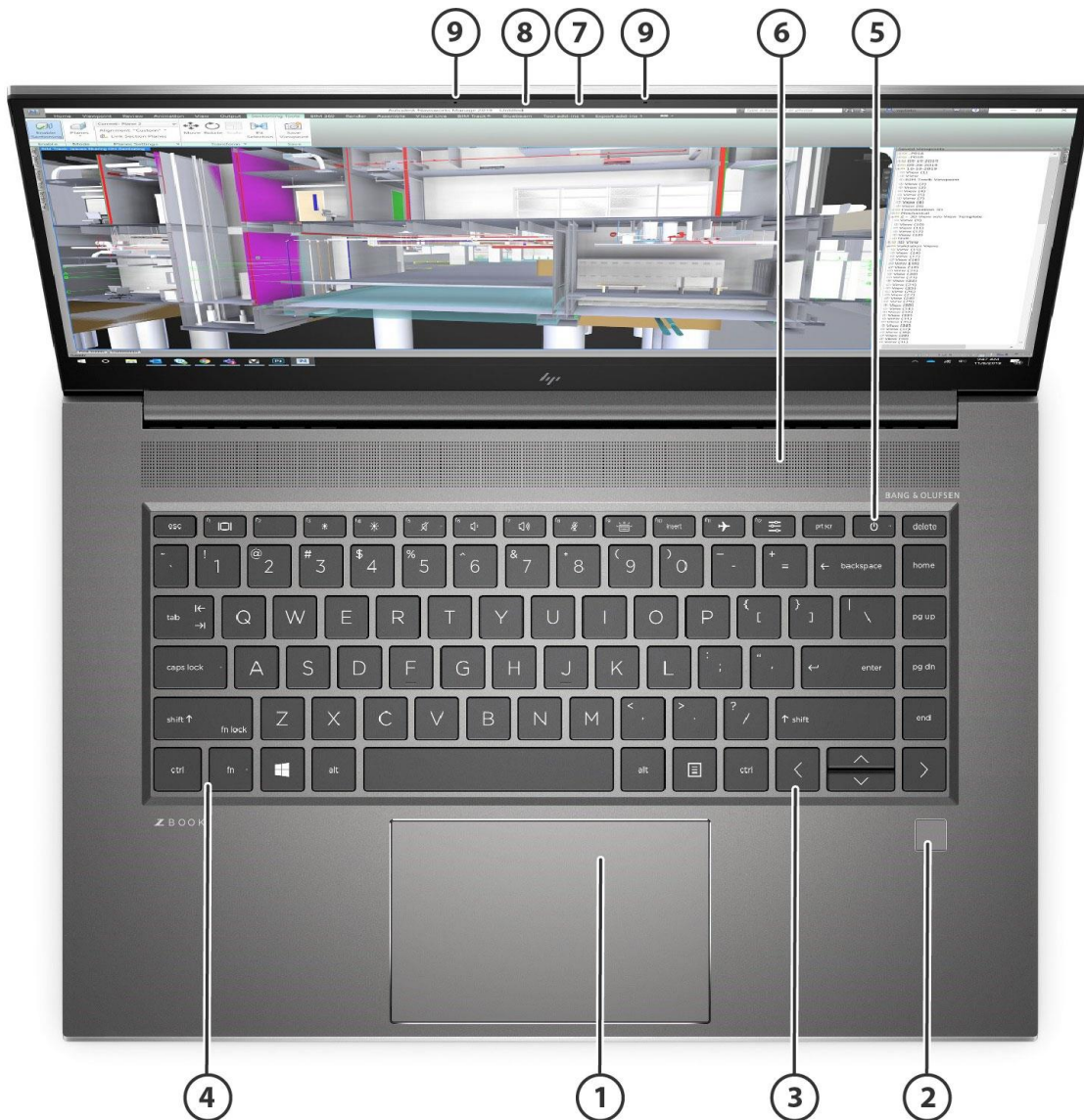


Overview

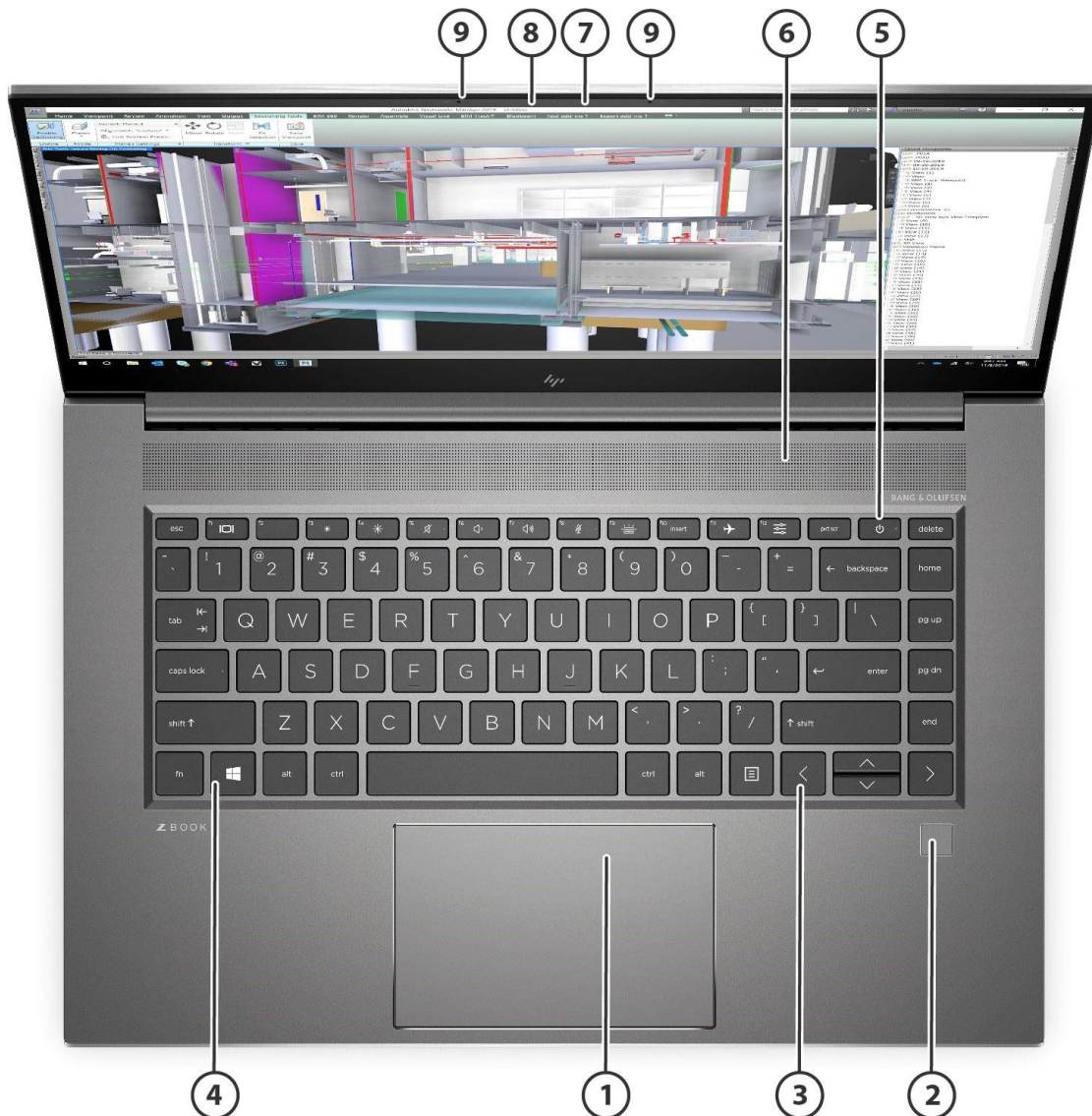
HP ZBook Studio G7 Mobile Workstation



Top View (Premium keyboard layout)

- | | |
|--|----------------|
| 1. Clickpad | 6. Speakers |
| 2. Fingerprint sensor (optional) | 7. Camera |
| 3. HP Premium backlit Keyboard | 8. IR Camera |
| 4. Layout: ctrl, fn, Windows, alt, space bar, alt, menu, ctrl layout | 9. Microphones |
| 5. Power button (or power on by opening the lid) | |

Overview



Top View (Z Command keyboard layout; US Only)

- | | |
|---|----------------|
| 1. Clickpad | 6. Speakers |
| 2. Fingerprint sensor (optional) | 7. Camera |
| 3. HP Z Command backlit Keyboard | 8. IR Camera |
| 4. Layout: fn, Windows, alt, ctrl, space bar, ctrl, alt, menu, layout | 9. Microphones |
| 5. Power button (or power on by opening the lid) | |

Overview



Left

- | | |
|---------------------------------------|--|
| 1. Nano security lock slot | 3. Side Vent |
| 2. USB 3.1 Gen 1 Type A charging port | 4. Stereo microphone in / headphone-out combo jack |



Right (configurations without NVIDIA RTX Graphics)

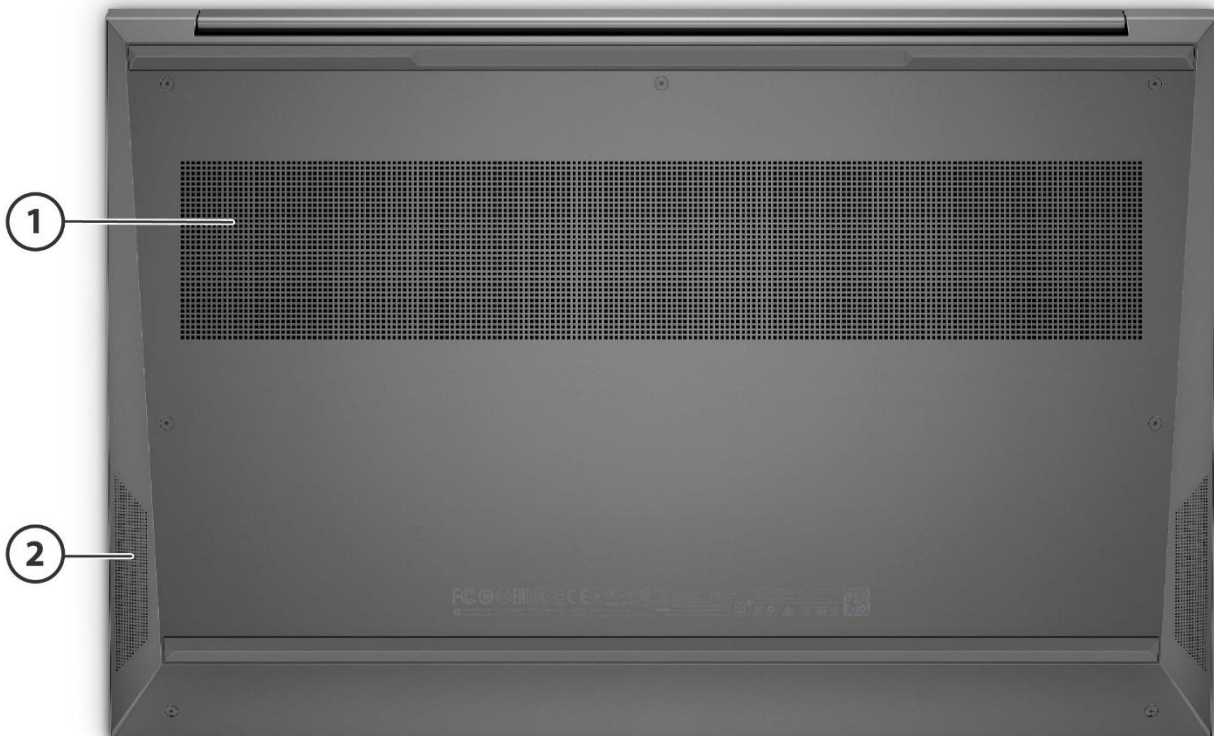
- | | |
|------------------------------------|--|
| 1. Battery Charging LED | 4. HDMI 2.0 with Discrete Graphics / HDMI 1.4 with UMA graphics (HDMI cable is not included) |
| 2. Power connector | 5. SD Card Reader (SD Media not included) |
| 3. 2 USB Type-C® with Thunderbolt™ | |

Overview



Right (configurations with NVIDIA RTX Graphics)

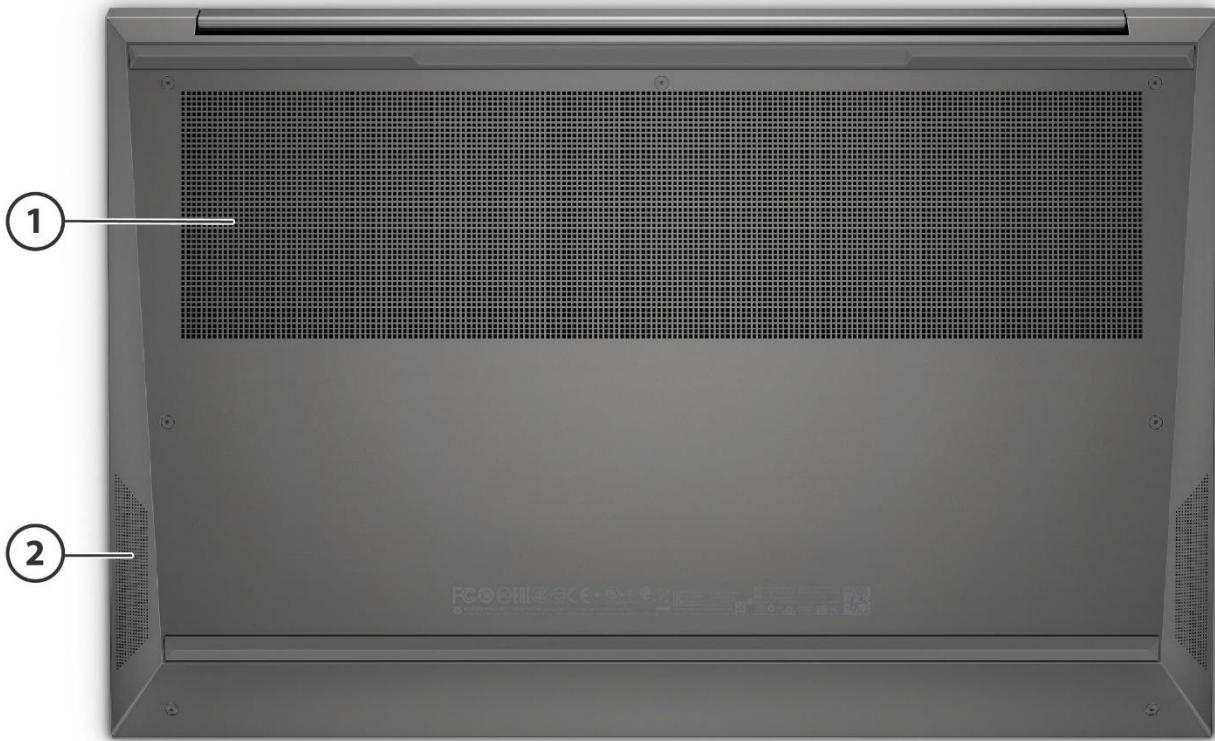
1. Battery Charging LED
2. 4.5mm Power connector
3. 2 USB Type-C® with Thunderbolt™
4. mini DisplayPort™ 1.4 (mini DisplayPort cable is not included)
5. SD 4.0 Card Reader (SD Media not included)



Bottom (configurations without NVIDIA RTX Graphics)

1. Fan Venting
2. Speakers

Overview



Bottom (configurations with NVIDIA RTX Graphics)

1. Fan Venting

2. Speakers

Overview

At A Glance

- Work anywhere without compromising on performance or security with Windows 10 Pro¹, powered by HP's collaboration and connectivity technology.
- Experience high-end visualization and seamlessly render your biggest projects with the next generation NVIDIA® Quadro® T-Series and RTX graphics²; Certified and supported for the apps you use every day.
- Take multitasking to the next level with up to the 10th gen Intel® Core™ i9 or Intel® Xeon® processor^{3,4,22} designed to handle complex, multithreaded apps like Adobe Premiere Pro®, and with fast clock speeds you can boost your speed on single threaded apps like Autodesk 3ds Max.⁵
- Power through projects with up to 32 GB SDRAM⁶ for fast rendering, editing and simulating.
- Blitz through multiple tasks and ditch external drives with up to 2 TB local NVMe storage⁷
- 4 Speakers (2 tweeters and 2 woofers) speakers custom tuned by Bang and Olufsen surround you in a rich sound space so you hear music the way the audio engineers intended. Featuring the most powerful speakers with the greatest levels of bass on any HP notebook.
- Connect to everything you need with a wide-range of connectivity options: Dual USB-C® Thunderbolt™, HDMI¹¹ (only on configurations without RTX Graphics) or mini DisplayPort™¹¹ (only on configurations with RTX graphics), USB 3.1 Type A charging port, headphone jack, and AC port.
- Choice of displays²:
 - 39.6 cm (15.6") diagonal 4K UHD (3840 x 2160) IPS eDP + PSR anti-glare, 100% DCI-P3, 600 nits VESA DisplayHDR 400 Certified Next Gen HP DreamColor Panel;
 - 39.6 cm (15.6") diagonal FHD (1920 x 1080) IPS eDP + PSR anti-glare, 100% sRGB at 400 nits low power (1W) panel;
 - 39.6 cm (15.6") diagonal FHD (1920 x 1080) IPS eDP + PSR anti-glare, 72% NTSC at 1000 nits HP Sure View Reflect Integrated Privacy Panel;
 - 39.6 cm (15.6") diagonal 4K UHD (3840 x 2160) UWVA eDP + PSR Brightview 100% DCI-P3, 400 nits OLED VESA DisplayHDR 500 True Black Certified panel with Corning® Gorilla® Glass 6 Touch Screen
- A completely revamped standby system means you're ready to work the moment inspiration strikes. With no sleep mode and no off mode, the modern standby keeps your rig connected and on demand whenever you need it.
- Transfer files over Wi-Fi® up to 3x faster with Wi-Fi 6¹²
- Have confidence with the HP's most secure mobile workstations.¹³ Instantly protect against visual hacking with HP Sure View Reflect¹⁴, and defend against firmware and malware attacks with HP Sure Start Gen6^{10,15} and HP Sure Sense.^{9,16}
- A highly recyclable & lightweight aluminum exterior with 5x the abrasion resistance of painted carbon fiber allows for a more durable, thin, and recyclable device.²¹
- HP ZBook Studio G7 is designed to undergo extensive MIL-STD 810H testing, and has passed 21 of the MIL-STD 810H tests.¹⁷
- Plug in to greater connectivity at your desktop with the HP Thunderbolt Dock for lightning-fast Thunderbolt™ 3¹⁸ transfers and the flexibility to run up to two external 4K displays.^{19, 20}

¹Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See <http://www.windows.com>.

²Sold separately or as an optional feature.

NVIDIA®, the NVIDIA® logo, NVIDIA Turing™ and NVIDIA® GeForce® are trademarks and/or registered trademarks of NVIDIA Corporation in the U.S. and other countries

³Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

⁴Intel® Turbo Boost technology requires a PC with a processor with Intel Turbo Boost capability. Intel Turbo Boost performance varies depending on hardware, software and overall system configuration. See www.intel.com/technology/turboboost for more information. "

⁵Adobe and Autodesk software sold separately.

⁶Up to 32GB memory is an optional, configurable feature.

⁷For hard drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30GB (for Windows 10) of system disk is reserved for system recovery software.

Overview

⁹ HP Sure Sense requires Windows 10 Pro or Enterprise. See product specifications for availability.

¹⁰ HP Sure Start Gen6 is available on select HP PCs.

¹¹ miniDisplayPort cables are sold separately; HDMI Cables are sold separately

¹² Wi-Fi 6 offers up to 3x faster file transfer speeds than Wi-Fi® 5 Based on Wi-Fi 5 80MHz and Wi-Fi 6 160MHz minimum requirements when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 802.11ax (Wi-Fi 6). Only available in countries where 802.11ax is supported

¹³ Based on HP's unique and comprehensive security capabilities at no additional cost among desktop workstation vendors as of Sept. 2017 on HP Mobile Workstations with 7th Gen and higher Intel® Processors.

¹⁴ HP Sure View integrated privacy screen is an optional feature that must be configured at purchase.

¹⁶ HP Sure Sense requires Windows 10 Pro or Enterprise. See product specifications for availability.

¹⁷ Testing is not intended to demonstrate fitness of U.S. Department of Defense (DoD) contract requirements or for military use. Test results are not a guarantee of future performance under these test conditions. Accidental damage requires an optional HP Accidental Damage Protection Care Pack.

¹⁸ HP Thunderbolt Dock with Thunderbolt™ 3 sold separately.

¹⁹ External displays sold separately.

²⁰ Optional hybrid graphics is required to run up to two external 4K displays.

²¹ HP Internal Testing conducted on July 2018, using ASTM International Standards Worldwide using test method ASTM D4060

²² Intel Xeon Processor is planned to be available in 2nd half of 2020.

NOTE: See important legal disclosures for all listed specs in their respective feature's sections.

Features

OPERATING SYSTEM

Preinstalled OS	Windows 10 Pro 64 - HP recommends Windows 10 Pro for business. ¹ Windows 10 Home 64 ^{1,2} Windows 10 Pro for Workstations 64 ¹ Ubuntu 20.04 ² FreeDOS 3.0
Supported OS⁴	Windows 10 64 Enterprise
Supported Version	HP tested Windows 10, version 1809 on this platform. For testing information on newer versions of Windows 10, please see: https://support.hp.com/document/c05195282 .

¹ Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See <http://www.windows.com>.

² Windows 10 Home 64 to be available in the 2nd half of 2020

³ Ubuntu 20.04 to be available in the 2nd half of 2020

⁴ Support to be tested and documented or web support only.

PROCESSOR

Intel® Xeon® W 10885M with Intel® UHD Graphics (2.4 GHz base frequency, up to 5.3 GHz with Intel® Turbo Boost Technology, 16 MB L3 cache, 8 cores) supporting Intel® vPro® technology^{1,2,3,4,5,6}

10th Generation Intel® Core™ i9 10885H with Intel® UHD Graphics (2.4 GHz base frequency, up to 5.3 GHz with Intel® Turbo Boost Technology, 16 MB L3 cache, 8 cores) supporting Intel® vPro® technology^{1,2,3,4,5}

10th Generation Intel® Core™ i7 10850H with Intel® UHD Graphics (2.7 GHz base frequency, up to 5.1 GHz with Intel® Turbo Boost Technology, 12 MB L3 cache, 6 cores) supporting Intel® vPro® technology^{1,2,3,4,5}

10th Generation Intel® Core™ i7 10750H with Intel® UHD Graphics (2.6 GHz base frequency, up to 5.0 GHz with Intel® Turbo Boost Technology, 12 MB L3 cache, 6 cores)^{1,2,3,4}

10th Generation Intel® Core™ i5 10400H with Intel® UHD Graphics (2.6 GHz base frequency, up to 4.6 GHz with Intel® Turbo Boost Technology, 8 MB L3 cache, 4 cores) supporting Intel® vPro® technology^{1,2,3,4,5}

¹ Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

² Processor speed denotes maximum performance mode; processors will run at lower speeds in battery optimization mode.

³ Intel® Turbo Boost performance varies depending on hardware, software and overall system configuration. Energy Efficient Turbo is a power management feature that can lower the maximum core ratio (frequency), if the CPU thinks it can achieve about the same performance as with the maximum turbo frequency. Energy Efficient Turbo feature is disabled in Comet Lake H in order to prioritize performance in DC mode. It can be changed in F10 BIOS settings. See www.intel.com/technology/turboboost for more information.

⁴ In accordance with Microsoft's support policy, HP does not support the Windows 8 or Windows 7 operating system on products configured with Intel and AMD 7th generation and forward processors or provide any Windows 8 or Windows 7 drivers on <http://www.support.hp.com>.

⁵ For full Intel® vPro® functionality, Windows, a vPro supported processor, vPro enabled Q370 chipset or higher and vPro enabled WLAN card are required. Some functionality, such as Intel Active management technology and Intel Virtualization technology, requires additional 3rd party software in order to run. Availability of future "virtual appliances" applications for

Features

Intel vPro technology is dependent on 3rd party software providers. Compatibility of this generation of Intel vPro technology-based hardware with future "virtual appliances" is yet to be determined.

⁶ Intel® Xeon® W 10885M is scheduled to be available in the 2nd half of 2020.

Features

CHIPSET

Intel® WM490 Chipset

INTEL® CORE™ I5 WITH VPRO/CORE I7 WITH VPRO TECHNOLOGY CAPABLE

Intel® Core™ i5 with vPro®, Core™ i7 with vPro®, Core™ i9 with vPro® and Xeon® with vPro® technology is a selectable feature that is available on units configured with select processors, a qualified Intel® WLAN module and a preinstalled Windows® operating system. It provides advances in remote manageability, security, energy efficient performance, and wireless connectivity. Intel® Active Management Technology (iAMT) offers built-in manageability and proactive security for networked mobile workstations, even when they are powered off* or when the operating system is inoperable. It can help identify threats before they reach the network, isolate infected systems, and update regardless of their power state.

¹ Requires a Windows operating system, network hardware and software, connection with a power source, and a direct (non-VPN) corporate network connection which is either cable or wireless LAN.

² Some functionality of Intel® Core™ i5 with vPro®/Core™ i7 with vPro®/Core™ i9 with vPro®/Xeon® with vPro® technology, such as Intel® Active Management technology and Intel® Virtualization technology, requires additional third-party software in order to run. Availability of future "virtual appliances" applications for Intel® Core™ i5 with vPro®/Core i7 with vPro®/XEON® with vPro® technology is dependent on third-party software providers. Compatibility with future "virtual appliances" is yet to be determined.

GRAPHICS

Integrated

Intel® UHD Graphics ^{1,2,3,4,5,6}

Supports up to 3 displays including the integrated display.

Supports: HD decode, DX12, Intel® Quick Sync Video,

Max resolution for external displays: HDMI 1.4 4096x2304 @30Hz; DisplayPort via USB-C® Thunderbolt™ 4096x2304 @60Hz

Discrete

NVIDIA® Quadro® T1000 supporting Max-Q Design (4 GB GDDR6 dedicated)^{2,4,6}

NVIDIA® Quadro® T2000 supporting Max-Q Design (4 GB GDDR6 dedicated)^{2,4,6}

NVIDIA® Quadro® RTX 3000 supporting Max-Q Design (6 GB GDDR6 dedicated)^{2,6,8}

NVIDIA® Quadro® RTX 4000 supporting Max-Q Design (8 GB GDDR6 dedicated)^{2,6,8}

NVIDIA® Quadro® RTX 5000 supporting Max-Q Design (16 GB GDDR6 dedicated)^{2,6,8,9}

Supports up to 4 displays through discrete graphics and dock

Supports: NVIDIA Surround Technology for NVIDIA GeForce Graphics

Max resolution for external displays: HDMI 1.4 4096x2304 @30Hz; DisplayPort via USB-C® Thunderbolt™ 4096x2304 @60Hz

¹ UHD content required to view UHD images.

² Both UMA & Discrete configurations support 3 independent displays when on the HP Thunderbolt Dock G2 (sold separately) - Max. resolution = 2.5K @60Hz (DP1) & 2.5K @60Hz (DP2) & FHD (VGA) OR 4K @60Hz (one DP Port) & 4K @60Hz (Type-C® output port using a Type C®-to-DP adapter).

³ Support HD decode, DX11, DX12, HDMI 1.4, HDCP 2.3 via DP up to 4K @ 60Hz and via HDMI up to 4K @ 30Hz

⁴ HDMI cable Sold Separately

Features

⁵ Shared video memory (UMA) uses part of the total system memory for video performance. System memory dedicated to video performance is not available for other use by other programs.

⁶ GPU configurations may be limited to specific GPU/Memory Configurations.

⁸ miniDP cable sold separately.

⁹ NVIDIA GeForce RTX 5000 graphic options available in 2nd half of 2020.

DISPLAY

Non-touch

- 39.6 cm (15.6") diagonal 4K UHD (3840 x 2160) IPS eDP + PSR anti-glare, 100% DCI-P3, 600 nits VESA DisplayHDR 400 Certified Next Gen HP DreamColor Panel ^{2,3,5,6}
- 39.6 cm (15.6") diagonal FHD (1920 x 1080) IPS eDP + PSR anti-glare, 100% sRGB at 400 nits (1W) low power panel ^{2,3,5,6}
- 39.6 cm (15.6") diagonal FHD (1920 x 1080) IPS eDP + PSR anti-glare, 72% NTSC at 1000 nits HP Sure View Reflect Integrated Privacy Panel ^{2,3,5,6}
- 39.6 cm (15.6") diagonal 4K UHD (3840 x 2160) UWVA eDP + PSR Brightview 100% DCI-P3, 400 nits OLED VESA DisplayHDR 500 True Black Certified panel with Corning® Gorilla® Glass 6 Touch Screen ^{2,3,5,6}

HP Virtual Reality⁷ Headset (sold separately)

- HP Reverb
- HP Reverb G2

¹ HP Sure View Reflect is optional and must be configured at purchase.

² UHD content required to view UHD images.

³ Resolutions are dependent upon monitor capability, and resolution and color depth settings.

⁵ Display options may be limited to specific CPU / GPU Configurations.

⁶ VESA DisplayHDR 400 and DisplayHDR 500 True Black certifications are pending.

⁷ Virtual Reality content is required to view Virtual Reality images

Features

STORAGE AND DRIVES*

- 1 M.2 Storage (PCIe NVMe™ SSD) slot¹
- 256 GB PCIe® Gen 3 x 4 NVMe™ M.2 2280 TLC SSD
- 1 TB PCIe® Gen 3 x 4 NVMe™ M.2 2280 TLC SSD
- 2 TB PCIe® Gen 3 x 4 NVMe™ M.2 2280 TLC SSD
- 512 GB PCIe® NVMe™ M.2 SED 2280 TLC SSD

¹M.2 Storage Slot does not support SATA drives
* For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35GB of disk is reserved for system recovery software.

DRIVE CONTROLLERS

M.2 Storage Bay (PCIe NVMe)	PCIe Gen 3 x 4 lanes NVMe Solid State Drive
SATA	Not supported
RAID	Not supported

MEMORY

- Maximum Memory
- 32 GB DDR4 non-ECC SDRAM^{1,2}
- Memory soldered down. Supports Dual Channel Memory³
- System Runs at: 2933

¹Memory is soldered down and not upgradeable
²Memory configurations may be limited to specific CPU / GPU Configurations.
³Due to the non-industry standard nature of some third-party memory modules, we recommend HP branded memory to ensure compatibility. If you mix memory speeds, the system will perform at the lower memory speed.

Features

NETWORKING/COMMUNICATIONS

WLAN

Intel® Wi-Fi 6 AX201 (2x2) and Bluetooth® 5 combo, vPro® ^{1,2}

Intel® Wi-Fi 6 AX201 (2x2) and Bluetooth® 5 combo, non-vPro® ¹

¹Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. The specifications for Wi-Fi 6 (802.11ax WLAN) are draft specifications and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ax WLAN devices. Only available in countries where 802.11ax is supported.

²Some functionality of vPro®, such as Intel Active management technology and Intel Virtualization technology, requires additional 3rd party software in order to run. Availability of future "virtual appliances" applications for Intel vPro® technology is dependent on 3rd party software providers. Compatibility with future "virtual appliances" is yet to be determined.

AUDIO/MULTIMEDIA

Audio

Audio by Bang & Olufsen, quad speakers (2 tweeters and 2 woofers), HP World Facing Microphone and dual array digital microphones, functions keys for volume up and down, combo microphone/headphone jack, HD audio with 150Hz Bass Roll off

Camera^{1,2}

720p HD with Temporal Noise Reduction webcam with IR

¹ HD content required to view HD images.

² Windows Hello face authentication utilizes a camera specially configured for near infrared (IR) imaging to authenticate and unlock Windows devices as well as unlock your Microsoft Passport.

Features

KEYBOARDS/POINTING DEVICES/BUTTONS & FUNCTION KEYS

Keyboard

HP Premium Quiet Keyboard, full-size, spill-resistant, backlit, with drain and DuraKeys, clickpad with image sensor and glass surface, multi-touch gestures and taps enabled

HP Premium Quiet Z Command Keyboard¹, full-size, spill-resistant, backlit, with drain and DuraKeys, clickpad with image sensor and glass surface, multi-touch gestures and taps enabled

Pointing Devices

Clickpad with multi-touch gestures enabled, taps enabled as default
Microsoft Precision Touchpad Default Gestures Support

Buttons and Function Keys

Discrete buttons provide easy access to the following features:

- F1 – Display Switching
- F2 – HP Sure View on/off (if configured)
- F3 – Brightness Down
- F4 – Brightness Up
- F5 – Audio mute
- F6 – Volume down
- F7 – Volume up
- F8 – Microphone mute
- F9 – Keyboard backlight
- F10 – Insert
- F11 – Airplane Mode on/off
- F12 – Programmable Key
- Print Screen
- Power Button on/off
- Delete
- Fn key lock

Hidden Function Keys:

- Fn+R=Break
- Fn+S=Sys Rq
- Fn+C=Scroll Lock
- Fn+W=Pause

¹Only available in the US, and optional

SOFTWARE AND SECURITY

Workstation ISV Certifications

See the latest list of certifications at: <http://www.hp.com/go/isv>

HP ZCENTRAL REMOTE BOOST SOFTWARE

The remote desktop solution for serious workstation users and their most demanding applications. Download at: <http://www.hp.com/go/RGS>

HP Performance Advisor

HP Performance Advisor enables optimal configuration of HP Mobile Workstations delivering stability and best performance. HP Performance Advisor will guide your system setup allowing a "custom" configuration that best matches the workstation to user requirements. Download at: <http://www.hp.com/go/performanceadvisor>

Software

Bing search for IE11
Buy Office

Features

HP Hotkey Support
HP Noise Cancellation Software
HP Performance Advisor⁸
HP Z Central Remote Boost Software²
Native Miracast support⁴
HP Connection Optimizer⁹

Security Management

Absolute persistence module⁶
HP Device Access Manager
HP FingerPrint Sensor
HP Manageability Integration Kit¹¹
HP Power On Authentication
HP Support Assistant
Security lock slot¹²
Trusted Platform Module TPM 2.0 Embedded Security Chip
Master Boot Record security
Pre-boot authentication
Microsoft Security Defender¹⁰
HP Client Security Manager¹⁷
HP BIOSphere Gen6⁵
HP Sure Recover Gen3¹³
HP Sure Start Gen6^{5, 15}
HP Secure Erase¹⁶
HP Sure Sense¹⁸

TPM

Model: Infineon SLB9670
Version: 7.63.3353.0
Revision: TPM 2.0
FIPS 140-2 Compliant: Yes with Convert TPM to 2.0 (FIPS 140-2) option

Fingerprint Sensor (Optional)

Voltage: 3.0-3.6V
Operating temperature: -20° - 85°C
Imaging current: 31mA
Wake on finger current: 40 uA
Capture rate: 30ms/frame
ESD Resistance: IEC 6100-4-2 4B (+/-15KV)
Detection Matrix: 363 dpi, sensing area 8x8 mm

Security Features

HP Fingerprint Sensor (optional)¹⁹
IR Camera with Windows Hello

For more information on HP Client Security Software Suite, refer to <http://www.hp.com/go/clientsecurity>.

² HP Z Central Remote Boost Software does not come preinstalled on Z Workstations but can be downloaded and run on all Z desktop and laptops without license purchase. With non-Z sender devices, purchase of perpetual individual license or perpetual floating license per simultaneously executing versions and purchase of ZCentral Remote Boost Software Support is required. RGS requires Windows, RHEL (7 or 8), UBUNTU 18.04 LTS, or HP ThinPro 7 operating systems. MacOS (10.13 or newer) operating system is only supported on the receiver side. Requires network access. The software is available for download at hp.com/ZCentralRemoteBoost.

⁴ Miracast is a wireless technology your PC can use to project your screen to TVs, projectors, and streaming media players that also support Miracast. You can use Miracast to share what you're doing on your PC and present a slide show. For more information: <http://windows.microsoft.com/en-us/windows-8/project-wireless-screen-miracast>.

⁵ HP BIOSphere Gen6 is available on select HP Pro, Elite and ZBook PCs. See product specifications for details. Features may vary depending on the platform and configurations.

Features

⁶ Absolute agent is shipped turned off, and will be activated when customers activate a purchased subscription. Subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. The Absolute Recovery Guarantee is a limited warranty. Certain conditions apply. For full details visit:

<http://www.absolute.com/company/legal/agreements/computrace-agreement>. Data Delete is an optional service provided by Absolute Software. If utilized, the Recovery Guarantee is null and void. In order to use the Data Delete service, customers must first sign a Pre-Authorization Agreement and either obtain a PIN or purchase one or more RSA SecurID tokens from Absolute Software.

⁸ HP Performance Advisor Software - HP Performance Advisor is ready and waiting to help you get the most out of your HP Workstation from day one—and every day after. Learn more or download at: <https://www8.hp.com/us/en/workstations/performance-advisor.html>

⁹ HP Connection Optimizer requires Windows 10.

¹⁰ Microsoft Defender Opt in and internet connection required for updates.

¹¹ HP Manageability Integration Kit can be downloaded from <http://www.hp.com/go/clientmanagement>.

¹² Nano Security lock slot is Lock sold separately.

¹³ HP Sure Recover Gen3: See product specifications for availability. Requires an open, wired network connection. You must back up important files, data, photos, videos, etc. before using HP Sure Recover to avoid loss of data. HP Sure Recover (Gen1) does not support platforms with Intel® Optane™.

¹⁵ HP Sure Start Gen6 is available on select HP PCs with Intel processors. See product specifications for availability.

¹⁶ For the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clear" sanitation method.

HP Secure Erase does not support platforms with Intel® Optane™.

¹⁷ HP Client Security Manager Gen5 requires Windows and is available on select HP Pro, Elite and ZBook PCs. See product specifications for details.

¹⁸ HP Sure Sense requires Windows 10 Pro or Enterprise. See product specifications for availability.

¹⁹ HP Fingerprint Sensor is optional.

Features

POWER

Power Supply

Up to 18 hours¹

HP Long Life 6-cell, 83 Wh Li-ion polymer²

Supports battery HP Fast Charge: approximately 50% in 30 minutes

HP Smart 150 W External AC Power Adapter³

HP Slim Smart 200 W External AC Power Adapter

¹ Battery life will vary depending on the product model, configuration, loaded applications, features, use, wireless functionality and power management settings. The maximum capacity of the battery will naturally decrease with time and usage. See MobileMark14 battery benchmark <https://bapco.com/products/mobilemark-2014/> for additional details.

² Supports HP Fast Charge Technology (50% of the charge in 30 minutes)

³ Not available with NVIDIA Quadro RTX graphics configurations

ENVIRONMENTAL

ENERGY STAR® certified and EPEAT® GOLD registered configurations available¹

Low halogen²

¹ Based on US EPEAT® registration according to IEEE 1680.1-2018 EPEAT®. Status varies by country. Visit www.epeat.net for more information.

² External power supplies, power cords, cables and peripherals are not low halogen. Service parts obtained after purchase may not be low halogen.

Features

WEIGHTS & DIMENSIONS

Dimensions (w x d x h)

35.4 x 23.46 x 1.79 cm - non-touch

35.4 x 23.46 x 1.75 cm – touch

13.93 x 9.24 x 0.70 in - non touch

13.93 x 9.24 x 0.69 in - touch

Weights

Starting at 3.84 lbs (1.74kg)

Weight varies by configuration and components.

PORTS/SLOTS

Right side

1 power connector

2 USB Type-C® (Thunderbolt™ 3)

1 HDMI or miniDP1.4 (NVIDIA Quadro RTX graphics configurations or higher) connector

1 SD 4.0 Media Reader^{1, 2}

Left side

1 USB 3.1 Gen 1 (charging);

1 headphone/microphone combo

¹ SD Media does not come with the device and requires compatible media in order to use the slot.

²SD 4.0 supports next generation secure digital and is compatible to SD, SDHC, SDXC media

SERVICE AND SUPPORT

3-year limited warranty options available, depending on country. Batteries have a default one-year limited warranty except for Long Life Batteries which will have same 1-year or 3-year limited warranty as the platform. Optional¹ HP Care Pack Services are extended service contracts which go beyond your standard limited warranties. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at <http://www.hp.com/go/cpc>.

¹Sold separately or as an optional feature. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product. Consult your local HP Customer Support Center for details.

Technical Specifications – System Unit

SYSTEM UNIT

Stand-Alone Power Requirements (AC Power)	Nominal Operating Voltage	19.5 V	
	Average Operating Power(MM14)	4.38W	
	Average Operating Power(idle)	495mW (MSC) , 2.693W (Idle)	System in idle mode + max panel brightness FHD panel : 400nits UHD panel : 600nits
	Integrated graphics	45W<CPU (Intel did not define TDP for iGPU)	Adapter Safety test condition
	Discrete Graphics	35W	
	Max Operating Power	Discrete < 105W UMA < 45W	
Temperature	Operating	32° to 95° F (0° to 35° C) (not writing optical)	
	Non-operating	41° to 95° F (5° to 35° C) (writing optical)	
Relative Humidity	Operating	10% to 90%, non-condensing	
	Non-operating	5% to 95%, 101.6° F (38.7° C) maximum wet bulb temperature	
Shock	Operating	40 G, 2 ms, half-sine	
	Non-operating	200 G, 2 ms, half-sine	
Random Vibration	Operating	0.75 grms	
	Non-operating	1.50 grms	
Maximum Altitude (unpressurized)	Operating	-50 to 10,000 ft (-15.24 to 3,048 m)	
	Non-operating	-50 to 40,000 ft (-15.24 to 12,192 m)	
Planned Industry Standard Certifications	UL	Yes	
	CSA	Yes	
	FCC Compliance	Yes	
	ENERGY STAR®	Yes	
	EPEAT®	Targeting Gold	
	ICES	Yes	
	Australia / NZ A-Tick Compliance	Yes	
	CCC	Yes	
	Japan VCCI Compliance	Yes	
	KCC	Yes	
	BSMI	Yes	
	CE Marking Compliance	Yes	
	MIL STD 810H	Yes, Passed 21 Tests	
	BNCI or BELUS	Yes	
	CIT	Yes	
	Saudi Arabian Compliance (ICCP)	Yes	
	SABS	Yes	

¹Configurations of the HP ZBook Studio G7 that are ENERGY STAR® qualified are identified as HP ZBook Studio G7 ENERGY STAR on HP websites and on <http://www.energystar.gov>.

Technical Specifications – Displays

DISPLAYS

39.6 cm (15.6") diagonal 4K UHD (3840 x 2160) IPS eDP + PSR anti-glare, 100% DCI-P3, 600 nits VESA DisplayHDR 400 Certified Next Gen HP DreamColor Panel	Outline Dimensions (W x H)	350.22 x 216.37(mm) max
	Active Area	344.22 x 193.62 (mm)
	Weight	300g max.
	Diagonal Size	15.6 inch
	Thickness	2.6 (mm) max
	Interface	eDP1.4
	Surface Treatment	Anti-Glare
	Touch enabled	No
	Contrast Ratio	1700:1 (typical)
	Refresh Rate	60 Hz
	Brightness	600 nit typical (Panel Only)
	Pixel Resolution	Pitch 3840 x 2160 (UHD)
	Backlight	RGB
	PPI	LED
	Color Gamut Coverage	DCI-P3 100%
	Color Depth	8 bits + 2 FRC
	Viewing Angle	UWVA 85/85/85/85

39.6 cm (15.6") diagonal FHD (1920 x 1080) IPS eDP + PSR anti-glare, 100% sRGB at 400 nits low power (1W) panel	Outline Dimensions (W x H)	349.46 x 215.9 max.
	Active Area	344.16 x 193.59 typ.
	Weight	310g max
	Diagonal Size	15.6
	Thickness	2.6t max.
	Interface	eDP 1.4
	Surface Treatment	Anti-glare (AG)
	Touch enabled	No
	Contrast Ratio	1200:1 (typ)
	Refresh Rate	60Hz
	Brightness	400nit typ.
	Pixel Resolution	Pitch 1920 x 1080 (FHD)
	Backlight	RGB
	PPI	LED
	Color Gamut Coverage	sRGB 100%
	Color Depth	8bit
	Viewing Angle	UWVA 85/85/85/85

Technical Specifications – Displays

39.6 cm (15.6") diagonal 4K UHD (3840 x 2160) UWVA eDP + PSR Brightview 100% DCI-P3, 400 nits OLED VESA DisplayHDR 500 True Black Certified panel with Corning® Gorilla® Glass 6 Touch Screen	Outline Dimensions (W x H)	348.348×216.202 (mm) max	
	Active Area	344.2176 x 193.6224 (mm)	
	Weight	200g max.	
	Diagonal Size	15.6 (inch)	
	Thickness	2.195(mm) max	
	Interface	eDP 1.4	
	Surface Treatment	Glare (BV)	
	Touch enabled	Yes	
	Contrast Ratio	100,000:1	
	Refresh Rate	60Hz	
	Brightness	400nit (Panel Only)	
	Pixel Resolution	Pitch	3840 x 2160 (UHD)
	Backlight	RGB	
	PPI	OLED	
	Color Gamut Coverage	DCI P3 100%	
	Color Depth	8 bits + 2 FRC	
	Viewing Angle	UWVA 85/85/85/85	
39.6 cm (15.6") diagonal FHD (1920 x 1080) IPS eDP + PSR anti-glare, 72% NTSC at 1000 nits HP Sure View Reflect Integrated Privacy Panel	Outline Dimensions (W x H)	349.52 x 205.39 max.	
	Active Area	344.16 x 193.59 typ.	
	Weight	370g max.	
	Diagonal Size	15.6"	
	Thickness	2.6mm / 4.5mm max. (PCB)	
	Interface	eDP	
	Surface Treatment	LCD	
	Touch enabled	Anti-glare (AG)	
	Contrast Ratio	No	
	Refresh Rate	1500:1	
	Brightness	60Hz	
	Pixel Resolution	Pitch	1920 x 1080 (FHD)
	Backlight	LED	
	PPI	141	
	Color Gamut Coverage	100% sRGB	
	Color Depth	8 bits	
	Viewing Angle	UWVA 85/85/85/85	

Technical Specifications – Storage

STORAGE AND DRIVES

256GB M.2 2280 NVMe PCIe-3x4 TLC SSD	Form Factor	M.2 2280	
	Capacity	256 GB	
	NAND Type	TLC	
	Height	0.09 in (2.3 mm)	
	Width	0.87 in (22 mm)	
	Weight	0.02 lb (<10 g)	
	Interface	PCIe NVMe Gen3X4	
	Form Factor	M.2 2280	
	Performance	Maximum Sequential Read	Maximum Sequential Write
		2580 MB/s ~ 2600 MB/s	1000 MB/s ~ 1100 MB/s
SSD 512GB 2280 PCIe-3x4 NVMe Self Encrypted OPAL2 Three Layer Cell	Form Factor	M.2 2280	
	Capacity	512 GB	
	NAND Type	TLC	
	Height	0.09 in (2.3 mm)	
	Width	0.87 in (22 mm)	
	Weight	0.02 lb (<10 g)	
	Interface	PCIe NVMe Gen3X4	
	Performance	Maximum Sequential Read	Maximum Sequential Write
		2800 MB/s ~ 2900 MB/s	1000 MB/s ~ 1800 MB/s
	Logical Blocks	1,000,215,215	
2	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]	
	Features	ATA Security (Option); TCG Opal 2.0 ; TRIM; L1.2	
		Note: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for system recovery software.	
SSD 1TB 2280 PCIe-3x4 NVMe Three Layer Cell single-sided	Form Factor	M.2 2280	
	Capacity	1TB	
	NAND Type	TLC	
	Height	0.09 in (2.3 mm)	
	Width	0.87 in (22 mm)	
	Weight	0.02 lb (<10 g)	
	Interface	PCIe NVMe Gen3X4	
	Performance	Maximum Sequential Read	Maximum Sequential Write
		2900 MB/s ~ 3000 MB/s	Up to 2000 MB/s
	Logical Blocks	2,000,409,264	
2	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]	
	Features	ATA Security, TRIM; L1.2	

Technical Specifications – Storage

Note: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for system recovery software.

SSD 2TB 2280 PCIe-3x4 NVMe Three Layer Cell single-sided	Form Factor	M.2 2280	
	Capacity	2 TB	
	NAND Type	TLC	
	Height	0.09 in (2.3 mm)	
	Width	0.87 in (22 mm)	
	Weight	0.02 lb (<10 g)	
	Interface	PCIe NVMe Gen3X4	
	Performance	Maximum Sequential Read	Maximum Sequential Write
		Up to 2900MB/s	Up to 2100 MB/s
	Logical Blocks	3,907,029,168	
2	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]	
	Features	ATA Security, TRIM; L1.2	

Note: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for system recovery software.

Technical Specifications – Networking

NETWORKING/COMMUNICATION

Intel® Wi-Fi 64 AX201 and Bluetooth® 5.0 802.11ax (2 x 2) (Supporting gigabit file transfer speeds) vPro®1*

Wireless LAN Standards

IEEE 802.11a
IEEE 802.11b
IEEE 802.11g
IEEE 802.11n
IEEE 802.11ac
IEEE 802.11ax
IEEE 802.11d
IEEE 802.11e
IEEE 802.11h
IEEE 802.11i
IEEE 802.11k
IEEE 802.11r
IEEE 802.11v

Interoperability

Wi-Fi certified

Frequency Band

802.11b/g/n/ax
• 2.402 – 2.482 GHz
802.11a/n/ac/ax
• 4.9 – 4.95 GHz (Japan)
• 5.15 – 5.25 GHz
• 5.25 – 5.35 GHz
• 5.47 – 5.725 GHz
• 5.825 – 5.850 GHz

Data Rates

• 802.11b: 1, 2, 5.5, 11 Mbps
• 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
• 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
• 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)
• 802.11ac : MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, ,80MHz & 160MHz)
• 802.11ax : MCS0 ~ MCS11, (1SS and 2SS) (20MHz, 40MHz, ,80MHz & 160MHz)

Modulation

Direct Sequence Spread Spectrum
OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM
, 1024QAM

Security¹

• IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only • AES-CCMP: 128 bit in hardware
• 802.1x authentication
• WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.
• WPA2 certification
• IEEE 802.11i
• WAPI

Network Architecture Models

Ad-hoc (Peer to Peer)
Infrastructure (Access Point Required)

Roaming

IEEE 802.11 compliant roaming between access points

Output Power²

• 802.11b : +18.5dBm minimum
• 802.11g : +17.5dBm minimum
• 802.11a : +18.5dBm minimum
• 802.11n HT20(2.4GHz) : +15.5dBm minimum
• 802.11n HT40(2.4GHz) : +14.5dBm minimum
• 802.11n HT20(5GHz) : +15.5dBm minimum
• 802.11n HT40(5GHz) : +14.5dBm minimum

Technical Specifications – Networking

	• 802.11ac VHT80(5GHz) : +11.5dBm minimum • 802.11ac VHT160(5GHz) : +11.5dBm minimum • 802.11ax HT40(2.4GHz) : +10dBm minimum • 802.11ax VHT160(5GHz) : +10dBm minimum
Power Consumption	• Transmit mode 2.0 W • Receive mode 1.6 W • Idle mode (PSP) 180 mW (WLAN Associated) • Idle mode 50 mW (WLAN unassociated) • Connected Standby 10mW • Radio disabled 8 mW
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode
Receiver Sensitivity³	• 802.11b, 1Mbps : -93.5dBm maximum • 802.11b, 11Mbps : -84dBm maximum • 802.11a/g, 6Mbps : -86dBm maximum • 802.11a/g, 54Mbps : -72dBm maximum • 802.11n, MCS07 : -67dBm maximum • 802.11n, MCS15 : -64dBm maximum • 802.11ac, MCS0 : -84dBm maximum • 802.11ac, MCS9 : -59dBm maximum • 802.11ax, MCS11(HT40): -59dBm maximum • 802.11ax, MCS11(VHT160): -58.5dBm maximum
Antenna Type	High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications
Form Factor	PCI-Express M.2 MiniCard with CNVi Interface
Dimensions	1. Type 2230 : 2.3 x 22.0 x 30.0 mm 2. Type 1216: 1.67 x 12.0 x 16.0 mm
Weight	1. Type 2230 : 2.8g 2. Type 126: 1.3g
Operating Voltage	3.3v +/- 9%
Temperature	Operating 14° to 158° F (-10° to 70° C) Non-operating -40° to 176° F (-40° to 80° C)
Humidity	Operating 10% to 90% (non-condensing) Non-operating 5% to 95% (non-condensing)
Altitude	Operating Non- 0 to 10,000 ft (3,048 m) operating 0 to 50,000 ft (15,240 m)
LED Activity	LED Amber – Radio Off; LED Off – Radio ON
HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0/5.1 Wireless Technology	
Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy : 0~79 (1 MHz/CH) BLE : 0~39 (2 MHz/CH)
Data Rates and Throughput	Legacy : 3 Mbps data rate; throughput up to 2.17 Mbps BLE : 1 Mbps data rate; throughput up to 0.2 Mbps Legacy : Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy : Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)

Technical Specifications – Networking

Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 9.5 dBm for BR and EDR.
Power Consumption	Peak (Tx): 330 mW Peak (Rx): 230 mW Selective Suspend: 17 mW
Bluetooth Software Supported	Microsoft Windows Bluetooth Software
Link Topology	
Power Management	Microsoft Windows ACPI, and USB Bus Support
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
Power Management	ETS 300 328, ETS 300 826
Certifications	Low Voltage Directive IEC950 UL, CSA, and CE Mark
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)
Security & Manageability	Intel® vPro® support with appropriate Intel® chipset components

Intel® Wi-Fi 61 AX201 and Bluetooth 5.0 (802.11ax 2 x 2, non-vPro®, supporting gigabit file transfer speeds) nonvPro®

Wireless LAN Standards

IEEE 802.11a
IEEE 802.11b
IEEE 802.11g
IEEE 802.11n
IEEE 802.11ac
IEEE 802.11ax
IEEE 802.11d
IEEE 802.11e
IEEE 802.11h
IEEE 802.11i
IEEE 802.11k
IEEE 802.11r
IEEE 802.11v

Interoperability

Frequency Band

Wi-Fi certified
802.11b/g/n/ax
• 2.402 – 2.482 GHz
802.11a/n/ac/ax
• 4.9 – 4.95 GHz (Japan)
• 5.15 – 5.25 GHz

Technical Specifications – Networking

	• 5.25 – 5.35 GHz • 5.47 – 5.725 GHz • 5.825 – 5.850 GHz
Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps • 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) • 802.11ac : MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, ,80MHz & 160MHz) • 802.11ax : MCS0 ~ MCS11, (1SS and 2SS) (20MHz, 40MHz, ,80MHz & 160MHz)
Modulation	Direct Sequence Spread Spectrum OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM , 1024QAM
Security¹	• IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only • AES-CCMP: 128 bit in hardware • 802.1x authentication • WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. • WPA2 certification • IEEE 802.11i • WAPI
Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)
Roaming	IEEE 802.11 compliant roaming between access points
Output Power²	• 802.11b : +18.5dBm minimum • 802.11g : +17.5dBm minimum • 802.11a : +18.5dBm minimum • 802.11n HT20(2.4GHz) : +15.5dBm minimum • 802.11n HT40(2.4GHz) : +14.5dBm minimum • 802.11n HT20(5GHz) : +15.5dBm minimum • 802.11n HT40(5GHz) : +14.5dBm minimum • 802.11ac VHT80(5GHz) : +11.5dBm minimum • 802.11ac VHT160(5GHz) : +11.5dBm minimum • 802.11ax HT40(2.4GHz) : +10dBm minimum • 802.11ax VHT160(5GHz) : +10dBm minimum
Power Consumption	• Transmit mode :2.0 W • Receive mode :1.6 W • Idle mode (PSP) 180 mW (WLAN Associated) • Idle mode :50 mW (WLAN unassociated) • Connected Standby/Modern Standby: 10mW • Radio disabled: 8 mW
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode
Receiver Sensitivity³	• 802.11b, 1Mbps : -93.5dBm maximum • 802.11b, 11Mbps : -84dBm maximum • 802.11a/g, 6Mbps : -86dBm maximum • 802.11a/g, 54Mbps : -72dBm maximum • 802.11n, MCS07 : -67dBm maximum • 802.11n, MCS15 : -64dBm maximum • 802.11ac, MCS0 : -84dBm maximum • 802.11ac, MCS9 : -59dBm maximum

Technical Specifications – Networking

Antenna Type	•802.11 ax, MCS11 (HT40): -59dBm maximum •802.11 ax, MCS11 (VHT160): -58.5dBm maximum High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications
Form Factor	PCI-Express M.2 MiniCard with CNVi Interface
Dimensions	1. Type 2230 : 2.3 x 22.0 x 30.0 mm 2. Type 1216: 1.67 x 12.0 x 16.0 mm
Weight	1. Type 2230 : 2.8g 2. Type 126: 1.3g
Operating Voltage	3.3v +/- 9%
Temperature	Operating 14° to 158° F (-10° to 70° C) Non-operating -40° to 176° F (-40° to 80° C)
Humidity	Operating 10% to 90% (non-condensing) Non-operating 5% to 95% (non-condensing)
Altitude	Operating Non-operating 0 to 10,000 ft (3,048 m) 0 to 50,000 ft (15,240 m)
LED Activity	LED Amber – Radio OFF; LED White – Radio ON
HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0/5.1 Wireless Technology	
Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy : 0~79 (1 MHz/CH) BLE : 0~39 (2 MHz/CH)
Data Rates and Throughput	Legacy : 3 Mbps data rate; throughput up to 2.17 Mbps BLE : 1 Mbps data rate; throughput up to 0.2 Mbps Legacy : Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy : Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 9.5 dBm for BR and EDR.
Power Consumption	Peak (Tx): 330 mW Peak (Rx): 230 mW Selective Suspend: 17 mW
Bluetooth Software Supported	Microsoft Windows Bluetooth Software
Link Topology	
Power Management	Microsoft Windows ACPI, and USB Bus Support
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer

Technical Specifications – Networking

LE Low Duty Cycle Directed Advertising
LE L2CAP Connection Oriented Channels
Train Nudging & Interlaced Scan
BT4.2 ESR08 Compliance
LE Secure Connection- Basic/Full
LE Privacy 1.2 –Link Layer Privacy
LE Privacy 1.2 –Extended Scanner Filter Policies
LE Data Packet Length Extension
FAX Profile (FAX)
Basic Imaging Profile (BIP)2
Headset Profile (HSP)
Hands Free Profile (HFP)
Advanced Audio Distribution Profile (A2DP)

Technical Specifications – Power

POWER

150 Watt Smart Slim AC Adapter	Dimensions	138x66x22mm
	Weight	unit: 325g +/- 10g
	Input	Input Efficiency 88% at 115 Vac and 89% at 230Vac
		Input frequency range 47 ~ 63 Hz
		Input AC current 2.7 A at 90 Vac and Maximum Load
	Output	Output power 150W
		DC output 19.5V
		Hold-up time 5ms at 115 Vac input
		Output current limit <16.0A
	Connector	4.5mm Barrel Type
	Environmental Design	Operating temperature 32° to 95° F (0° to 35° C)
		Non-operating (storage) temperature -4° to 185° F (-20° to 85° C)
		Altitude 0 to 16,400 ft (0 to 5,000 m)
		Humidity 20% to 95%
		Storage Humidity 10% to 95%
	EMI and Safety Certifications Eg: *CE Mark - full compliance with LVD and EMC directives * Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. * MTBF - over 200,000 hours at 25°C ambient condition.	

200 Watt Smart Slim AC Adapter	Dimensions	152x73x23.5mm
	Weight	unit: 530g +/- 10g
	Input	Input Efficiency 88% at 115 Vac and 89% at 230Vac
		Input frequency range 47 to 63 Hz
		Input AC current 2.9 A at 90 Vac and Maximum Load
	Output	Output power 200W
		DC output 19.5V
		Hold-up time 5ms at 115 Vac input
		Output current limit <16.0A
	Connector	4.5mm Barrel Type
	Environmental Design	Operating temperature 32° to 95° F (0° to 35° C)

Technical Specifications – Power

Non-operating (storage) temperature	-4° to 185° F (-20° to 85° C)
Altitude	0 to 16,400 ft (0 to 5000m)
Humidity	5% to 95%
Storage Humidity	5% to 95%

EMI and Safety Certifications Eg:
*CE Mark - full compliance with LVD and EMC directives
* Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE.
* MTBF - over 200,000 hours at 25°C ambient condition.

Technical Specifications – Power

HP 6-cell Long Life Li-Ion (83 WHr)	Dimensions (H x W x L)	7.78x71.05x316.1 mm (0.306 x 2.797 x 12.44 inch)	
	Weight	0.305kg(0.67lb)	
	Cells/Type	3cell Lithium-Ion Polymer cell	
	Energy	Voltage	11.58V
		Amp-hour capacity	7.17Ah / 6.88Ah
		Watt-hour capacity	83Wh
	Temperature	Operating (Charging)	32° to 113° F (0° to 45° C)
		Operating (Discharging)	14° to 122° F (-10° to 60° C)
	Fuel Gauge LED	NA	
	Warranty	1-year ⁶	
	Optional Travel Battery Available	No	

Technical Specifications – Environmental

ENVIRONMENTAL DATA

Eco-Label Certifications & declarations

This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:

- IT ECO declaration
- US ENERGY STAR®
- EPEAT® Gold registered in the United States. See <http://www.epeat.net> for registration status in your country.

System Configuration

The configuration used for the Energy Consumption and Declared Noise Emissions data for the Notebook model is based on a “Typically Configured Notebook”.

Energy Consumption (in accordance with US ENERGY STAR® test method)

	115VAC, 60Hz	230VAC, 50Hz	100VAC, 60Hz
Normal Operation (Short idle)	9.62 W	10.54 W	9.37 W
Normal Operation (Long idle)	0.95 W	1.07 W	0.98 W
Sleep	0.95 W	1.07 W	0.98 W
Off	0.36 W	0.47 W	0.34 W

NOTE:

Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family. HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.

Heat Dissipation*

	115VAC, 60Hz	230VAC, 50Hz	100VAC, 60Hz
Normal Operation (Short idle)	32.9004 BTU/hr	36.0468 BTU/hr	32.0454 BTU/hr
Normal Operation (Long idle)	3.249 BTU/hr	3.6594 BTU/hr	3.3516 BTU/hr
Sleep	3.249 BTU/hr	3.6594 BTU/hr	3.3516 BTU/hr
Off	1.2312 BTU/hr	1.6074 BTU/hr	1.1628 BTU/hr

***NOTE:** Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.

Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)

	Sound Power (L_{WAd} , bels)	Sound Pressure (L_{pAm} , decibels)
Typically Configured – Idle	2.5	22
Fixed Disk – Random writes	3.6	35.5

Longevity and Upgrading

This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include:

- 1 M.2 2280 PCIe Gen 3 x 4 NVMe Solid State Drive Slot (does not support SATA M.2 2280 drives)

Spare parts are available throughout the warranty period and or for up to “5” years after the end of production.

Batteries

This battery(s) in this product comply with EU Directive 2006/66/EC

Technical Specifications – Environmental

Batteries used in the product do not contain:

Mercury greater than 1ppm by weight

Cadmium greater than 20ppm by weight

Battery description: CR2032 (coin cell)

Battery type: Lithium

Additional Information

- This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC.
- This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC.
- This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986).
- This product is in compliance with the IEEE 1680 (EPEAT) standard at the gold level, see www.epeat.net
- Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043.
- This product contains 7.8% post-consumer recycled plastic (by wt.)
- This product is 96.1% recycle-able when properly disposed of at end of life.

Packaging Materials

External:	PAPER/Corrugated	1292 g
	PAPER/Paper	20 g
	PAPER/Molded pulp	307 g
Internal:	PLASTIC/Polyethylene low density - LDPE	10 g
	PLASTIC/Polyester	10 g
	PLASTIC/Polypropylene - PP	7 g

The plastic packaging material contains at least 50% recycled content.

The corrugated paper packaging materials contains at least 70% recycled content.

Material Usage

This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at

<http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf>):

- Asbestos
- Certain Azo Colorants
- Certain Brominated Flame Retardants – may not be used as flame retardants in plastics
- Cadmium
- Chlorinated Hydrocarbons
- Chlorinated Paraffins
- Formaldehyde
- Halogenated Diphenyl Methanes
- Lead carbonates and sulfates
- Lead and Lead compounds
- Mercuric Oxide Batteries
- Nickel – finishes must not be used on the external surface designed to be frequently handled or carried by the user.
- Ozone Depleting Substances
- Polybrominated Biphenyls (PBBs)
- Polybrominated Biphenyl Ethers (PBEBs)
- Polybrominated Biphenyl Oxides (PBBOs)
- Polychlorinated Biphenyl (PCB)

Technical Specifications – Environmental

- Polychlorinated Terphenyls (PCT)
- Polyvinyl Chloride (PVC) – except for wires and cables, has been voluntarily removed from most applications.
- Radioactive Substances
- Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)

Packaging Usage

HP follows these guidelines to decrease the environmental impact of product packaging:

- Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials.
- Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
- Design packaging materials for ease of disassembly.
- Maximize the use of post-consumer recycled content materials in packaging materials.
- Use readily recyclable packaging materials such as paper and corrugated materials.
- Reduce size and weight of packages to improve transportation fuel efficiency.
- Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.

End-of-life Management and Recycling

HP offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: <http://www.hp.com/go/reuse-recycle> or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.

The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the HP web site at: <http://www.hp.com/go/recyclers>. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.

HP Inc. Corporate Environmental Information

For more information about HP's commitment to the environment:

Global Citizenship Report

<http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html>

Eco-label certifications

<http://www8.hp.com/us/en/hp-information/environment/ecolabels.html>

ISO 14001 certificates:

<http://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c04755842>

and

<http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf>

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Date of change:	Version History:		Description of change:
September 28, 2020	From v1 to v2	Changed	WEIGHTS & DIMENSIONS section
October 1, 2020	From v2 to v3	Changed	At A Glance, STORAGE AND DRIVES and SOFTWARE AND SECURITY sections